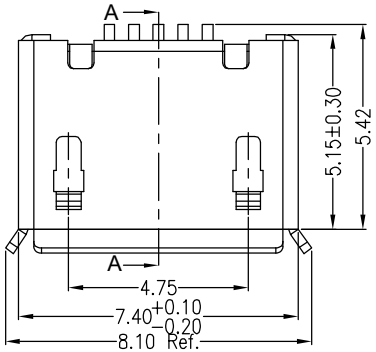
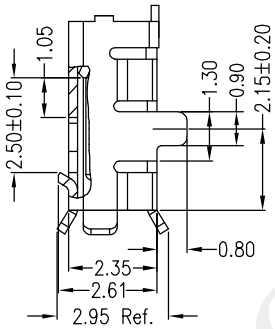
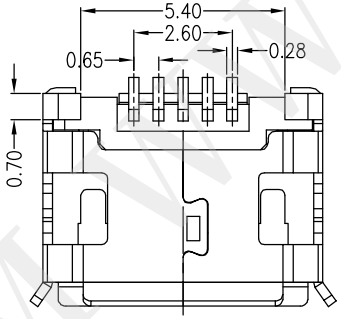
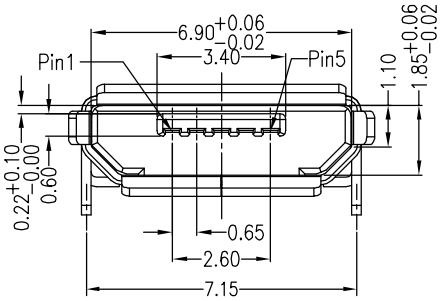


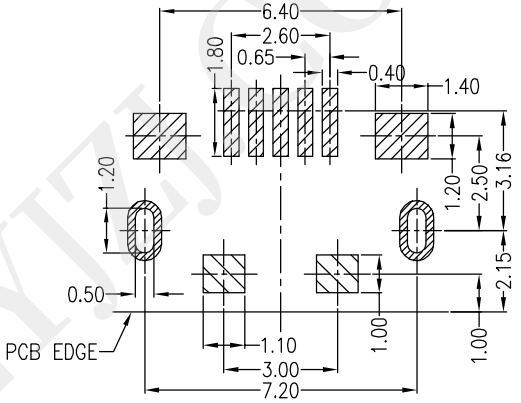

SECTION A-A'




RECOMMANDED PCB LAYOUT

Note:
1.Material:
- 1.1 Housing: High temperature thermoplastic with g.f,UL94v-0
- 1.2 Contact: copper alloy,t=0.20mm
- 1.3 Shell: copper alloy,t=0.25mm

2.Specification:
- 2.1 Current rating: 1 A Max.
- 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
- 2.3 Contact resistance: 50 mW Max.
- 2.4 Insulation resistance: 100 MW Min.
- 2.5 Total mating force: 3.57 Kgf Max.
- 2.6 Total unmating force: 1.0 Kgf Min.0.81~2.05 Kgf Min.
- 2.7 Temperature range: -30°C~80°C

深圳市华宇创精密电子有限公司

| | | | |
|---|---|---|---|
| TOLERANCE: X.X ±0.30, X.XX ±0.25, X.XXX ±0.15, X.° ±2°, X.X° ±0.5° | DRAWED BY: 陈一鸣 | DATE: 2014-02-23 | PART NAME: MICRO USB 7.2加固无柱有边 |
| | CHECKED BY: 马跃 | DATE: 2014-02-23 | PART NO. HYC117-USBD05-715 |
| UNIT: mm [inch] | APPROVED BY: 柯南 | DATE: 2014-02-23 | MOLD NO. |
| SCALE:1:1 SIZE: A4 | | | DRAW NO: HYC-USB18031423 |
| | | | SHEET NO. 1 OF 1 |

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